



Product Change Notification: DSN0-09GUUD527

Date:

25-Aug-2026

Product Category:

Memory

Notification Subject:

CCB 7830 Final Notice: Qualification of MMT as an additional assembly site for selected SST26WF016B, SST26WF016BA, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26VF032B, SST26VF032BA, SST26WF064C, SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A, SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B, SST26VF064B, SST26VF064BA and SST25PF020B device families available in 8L WSON (6x5x0.8mm) package.

Affected CPNs:

[DSNO-09GUUD527_Affected_CPN_08252026.pdf](#)

[DSNO-09GUUD527_Affected_CPN_08252026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected SST26WF016B, SST26WF016BA, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26VF032B, SST26VF032BA, SST26WF064C, SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A, SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B, SST26VF064B, SST26VF064BA and SST25PF020B device families available in 8L WSON (6x5x0.8mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Final PCN Issue Date									X												
Estimated Implementation Date												X									

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 11, 2025: Issued initial notification.
April 23, 2026: Issued final notification. Provided estimated first ship date to be on May 11, 2026.
August 25, 2026: Re-issued final notification to attached the Qualification Report.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-09GUUD527_Pre_and_Post Change Summary.pdf
PCN_DSNO-09GUUD527_Qualification Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

SST26VF032BAT-104I/MF

SST25VF040B-50-4I-QAE-T

SST26VF016B-80E/MF

SST26VF020A-104I/MF

SST26VF040A-104I/MF

SST25VF020B-80-4C-QAE

SST25VF080B-50-4C-QAF-T

SST25VF040B-50-4C-QAF-T

SST25PF020B-80-4C-QAE-T

SST25VF080B-50-4I-QAE-T

SST25VF080B-50-4I-QAF-T

SST25VF040B-50-4I-QAF-T

SST25VF020B-80-4I-QAE-T

SST26VF080AT-104I/MF

SST26VF016B-104I/MF

SST26VF016B-104I/MFA24

SST26VF016B-104V/MF

SST26VF080A-80E/MF

SST26WF080B-104I/MF

SST26WF080BA-104I/MF

SST26WF040B-104I/MF

SST26WF040BA-104I/MF

SST26VF032B-104V/MF

SST26VF032B-104I/MF

SST26VF032BA-104I/MF

SST26WF064C-104I/MF

SST26VF064BEUI-104I/MF

SST26VF040AT-104I/MF

SST26VF020AT-104I/MF

SST26VF032BT-104V/MF

SST26VF064B-104V/MF

SST26VF064BT-104V/MF

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SST26VF064BAT-104I/MF

SST26VF064BA-104I/MF

SST26VF064B-104I/MF

SST26VF016B-104I/MF-RN

SST26VF040A-80E/MF

SST26VF020A-80E/MF

SST25VF080B-50-4I-QAE

SST25VF080B-50-4I-QAF

SST25VF020B-80-4I-QAE

SST26VF080A-104I/MF

SST25VF040B-50-4I-QAF

SST26WF040BT-104I/MF

SST26WF040BAT-104I/MF

SST25VF020B-80-4C-QAE-T

SST25VF080B-50-4C-QAF

SST25VF040B-50-4C-QAF

SST25PF020B-80-4C-QAE

SST26WF016B-104I/MF

SST26WF016BA-104I/MF

SST26WF016BT-104I/MF

SST26WF016BAT-104I/MF

SST26WF080BT-104I/MF

SST26WF080BAT-104I/MF

SST25VF040B-50-4I-QAE

SST26VF064BEUIT-104I/MF

SST26VF080AT-80E/MF

SST26VF040AT-80E/MF

SST26VF020AT-80E/MF

SST26WF064CT-104I/MF

SST26VF016BT-104V/MF

SST26VF016BT-80E/MF

SST26VF016BT-104I/MF-RN

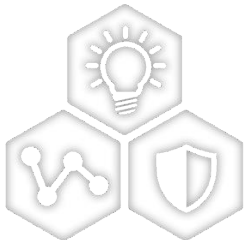
SST26VF016BT-104I/MF

SST26VF032BT-104I/MF

CCB 7830
Pre and Post Change Summary
PCN #: DSNO-09GUUD527

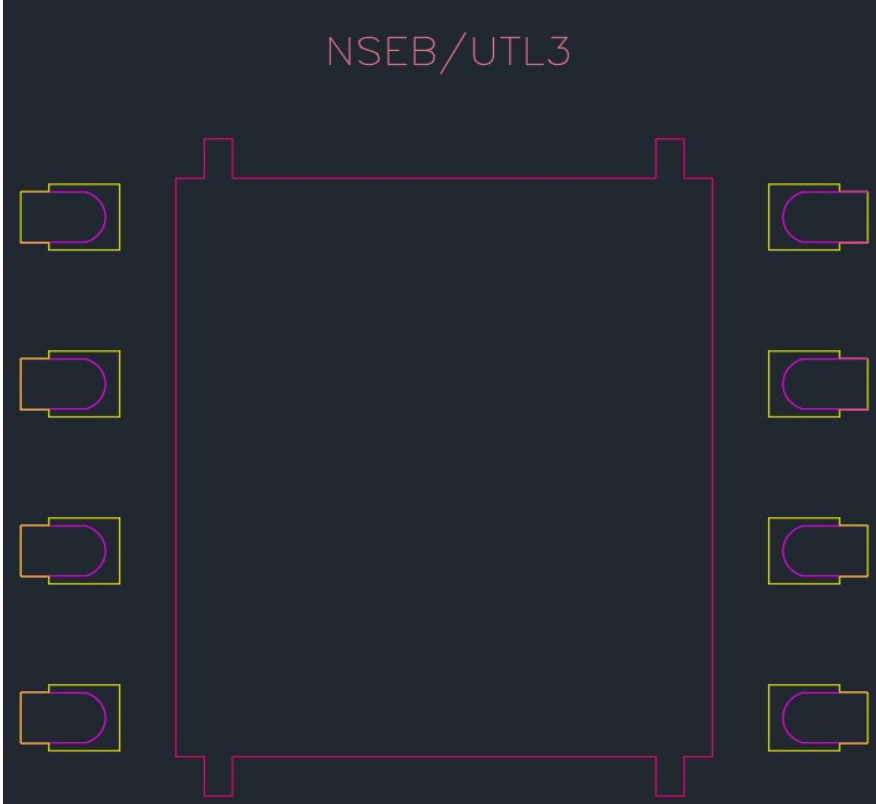
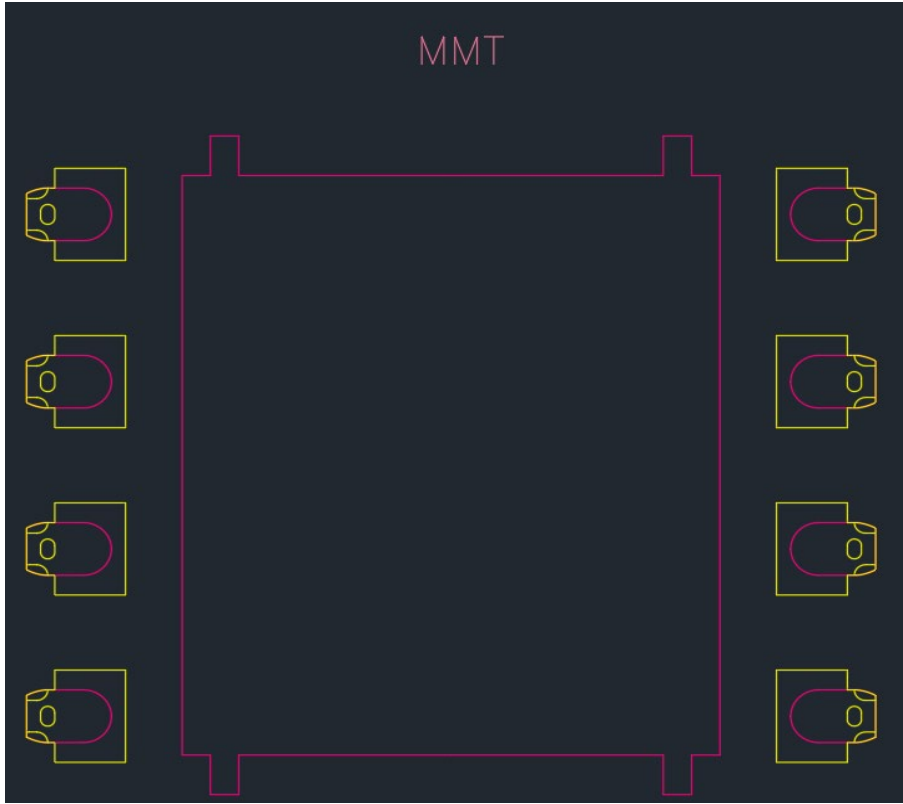


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Lead Frame Comparison

UTL-1 (NSEB)	UTL-3	MMT
NSEB/UTL3  Note: Not to scale		MMT  Note: Not to scale



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: DSNO-09GUUD527

Date:

August 6, 2026

**Qualification of MMT as an additional assembly site for selected
SST26WF016B, SST26WF016BA, SST26WF080B,
SST26WF080BA, SST26WF040B, SST26WF040BA,
SST26VF032B, SST26VF032BA, SST26WF064C,
SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A,
SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B,
SST26VF064B, SST26VF064BA and SST25PF020B device
families available in 8L WSON (6x5x0.8mm) package. This is a
Q006 Grade 1 Qualification.**

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for selected SST26WF016B, SST26WF016BA, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26VF032B, SST26VF032BA, SST26WF064C, SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A, SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B, SST26VF064B, SST26VF064BA and SST25PF020B device families available in 8L WSON (6x5x0.8mm) package. This is a Q006 Grade 1 Qualification.

CN:	E000286120
QUAL ID:	R2600518
QUAL ID Rev.:	A
MP CODE:	S01029U3XV01
Part No.:	SST26VF064B-104V/MF70SV01
Bonding No.:	BD-003648-01
CCB No.:	7830

Lead Frame

Paddle Size:	150x173
Material:	A194
DAP Surface Prep:	Bare Cu
Treatment	Roughening LF
Process:	Etched LF
Lead Lock:	Dimple
Part Number:	10100878
Lead Plating:	Matte Tin

Bond Wire

Wire:	CuPdAu wire
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Die Attach Material

Epoxy:	QMI519
Conductive:	Yes

Mold Compound

Mold Compound:	G700LTD
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Package

Type:	8L WSON
Package Size:	6x5x0.8mm

Manufacturing Information

Assembly Lot No.
MMT-270400943.000
MMT-270401555.000
MMT-270401558.000

Result: **Pass**

Conclusion:

Qualification of S0102 mask / SST26VF064B-104V/MF70SV01 product / CuPdAu wire in 8L WSON 6x5x0.8mm package at MMT site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C Electrical Test System: NEXTEST_GV2X - 25°C, 105°C and 125°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass	
High Temp Storage	175°C / 500 hours Electrical Test System: NEXTEST_GV2X - 25°C, 105°C and 125°C	JESD22-A103	45 units each lot / 3 lots	0/45, 0/45, 0/45	Pass	WBP 0/3, 0/3, 0/3; WBS 0/3, 0/3, 0/3
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles Electrical Test System: NEXTEST_GV2X - 25°C, 105°C and 125°C	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	WBP 0/3, 0/3, 0/3; WBS 0/3, 0/3, 0/3
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 3.6V Electrical Test System: NEXTEST_GV2X - 25°C, 105°C and 125°C	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	WBP 0/3, 0/3, 0/3; WBS 0/3, 0/3, 0/3
Unbiased HAST	+130°C / 85%RH / 96 hours Electrical Test System: NEXTEST_GV2X - 25°C	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5 units / 1 lot	0/5	Pass	